

IN THE CLAIMS:

Please cancel Claim 7 without prejudice or disclaimer of subject matter.

Please amend Claims 1 and 6 as shown below. The claims, as currently pending in the application, read as follows:

1. (Currently Amended) A semiconductor laser array comprising:

a chip having a plurality of luminous spots, said chip having buried heterojunction type lasers; and

a mount for mounting said chip by means of solder, said chip being soldered to said mount in a fashion of junction down,

wherein said chip projects from a corresponding end facet of said mount with a side of said chip having said plurality of luminous spots projecting away from the corresponding end facet of said mount, ~~semiconductor lasers of the semiconductor laser array are buried heterojunction type lasers,~~ and

wherein ~~said chip is soldered to said mount in a fashion of junction down while said chip projects from a corresponding end facet of said mount with a side of said chip having said plurality of luminous spots projecting away from the corresponding end facet of said mount~~ has a length between 200  $\mu$ m and 300  $\mu$ m in a resonator length direction and projects from the corresponding end facet of said mount in the resonator length direction by a predetermined amount such that residual stresses near each of the plurality of luminous spots caused by the soldering are reduced so as to maintain an angle of polarization between the plurality of luminous spots within a predetermined amount.

2. (Original) A semiconductor laser array according to claim 1, wherein said mount is made of silicon.

3. and 4. (Canceled)

5. (Original) A semiconductor laser array according to claim 1, wherein said plurality of luminous spots are driven independently.

6. (Currently Amended) An optical scanner comprising:

a semiconductor laser array, said semiconductor laser array including a chip having a plurality of luminous spots, said chip having buried heterojunction type lasers, and a mount for mounting said chip by means of solder, said chip being soldered to said mount in a fashion of junction down;

a rotary mirror for deflecting laser beams emitted from said semiconductor laser array; and

a focusing lens made of plastic material for focusing the laser beams deflected by said rotary mirror onto a surface to be scanned;

wherein said chip projects from a corresponding end facet of said mount with a side of said chip having said plurality of luminous spots projecting away from the corresponding end facet of said mount, ~~semiconductor lasers of the semiconductor laser array are buried heterojunction type lasers, and~~

wherein ~~said chip is soldered to said mount in a fashion of junction down~~

~~and while said chip projects from a corresponding end facet of said mount with a side of said chip having said plurality of luminous spots projecting away from the corresponding end facet of said mount~~ has a length between 200  $\mu\text{m}$  and 300  $\mu\text{m}$  in a resonator length direction and projects from the corresponding end facet of said mount in the resonator length direction by a predetermined amount such that residual stresses near each of the plurality of luminous spots caused by the soldering are reduced so as to maintain an angle of polarization between the plurality of luminous spots within a predetermined amount.

7. (Cancelled)